

Electronic **BALVER ZINN**[®]

Technical Data Sheet

BALVER ZINN SOLDER

SN97C (SnAg3.0Cu0.5)

SN97Ce (SnAg3.0)

General Information

BALVER ZINN SOLDER SN97C (SnAg3.0Cu0.5) is a lead-free* solder that is well known in Japan. This alloy was tested extensively by IPC and propagated as a worldwide standard solder. Established for a long time in Japanese electronics production. **BALVER ZINN SOLDER SN97C** has been developed for wave soldering, selective soldering and dip soldering applications. It is a slightly hypoeutectique alloy with a melting range of only 1°C! **BALVER ZINN SOLDER SN97Ce** (SnAg3.0) is a refill alloy with a low copper content, to maintain the copper content of the solder bath within due process limits. When using solders containing silver, the high copper dissolution may cause problems, particularly at higher process temperatures, and small line dimensions. For such applications **BALVER ZINN** recommends to use the highly reliable **BALVER ZINN SOLDER SN100C** to reduce copper dissolution.

***BALVER ZINN SOLDER SN97C** does not contain hazardous substances beyond the limits prescribed by EU Directive 2002/95/EG ("RoHS")

Further information is available in the **BALVER ZINN information „Lead free wave soldering.“** Technical information and Data Sheets can be found on our website (www.BALVERZINN.com). You can also obtain all information and documents directly from **BALVER ZINN**.

BALVER ZINN Production Programme

The **BALVER ZINN** production programme also includes solder pastes, flux and solder wires. Beside the **SN97C** product family, **BALVER ZINN** offers additional unpatented and patented solder alloys for wave soldering, reflow and rework.

General Process Information

To avoid high solder losses by dross, nitrogen hoods can be applied in wave soldering. Like all silver-containing solders with a high amount of tin, **BALVER ZINN SOLDER SN97C** severely affects pots and pumps, which therefore need to be sufficiently coated. Solder joints with **BALVER ZINN SOLDER SN97C** are not bright and shiny as with tin lead alloys. They show a rough, coarse and dendritic structure, caused by the formation of primary tin crystals during the solidification of the molten metal. In accordance with IPC standards, the typical "micro-cracks" are not quality decreasing characteristics. A differentiation between a good and a "cold" solder joint is not possible. **BALVER ZINN** conducts complimentary, regular solder bath analyses to determine a specific bath top-up schedule and avoid problems caused by an excessive level of impurities.

Conditions for Wave Soldering

- Solder bath temperature 260-275°C.
- Before entering the wave, the printed circuit boards should be 10–20°C warmer than for tin-lead applications (Sn63Pb37). Usual conditions are 110-135°C, measured on the top-side.
The old rule applies: "Do not try to use the wave for preheating!"
- The contact time in the wave has to be increased due to slower wetting in comparison with tin lead
- We recommend refilling with **BALVER ZINN SOLDER SN97Ce**, to keep the copper content stable (all PCB surfaces except from NiAu). The copper content should be maintained between 0,4% and 0,85%.

Information on Patent Situation

BALVER ZINN SOLDER SN97C is protected by patents. **BALVER ZINN** normally offers this alloy with prepaid license fees to protect customers from patent infringements. Since the composition of the solder joint is also covered by patents, the lead-free tin copper solder **SN97Ce** is also offered with license fees in order to avoid possible patent infringements.

Electronic **BALVER ZINN**[®]

Technical Data Sheet

BALVER ZINN SOLDER

SN97C (SnAg3.0Cu0.5)

SN97Ce (SnAg3.0)

Physical properties of SN97C / SN97Ce in comparison with tin-lead

	SN97C SnAg3.0Cu0.5	SN97Ce SnAg3.0	Sn63Pb37
Melting point °C	217 -218	221	183
Specific Gravity g/cm ³	7.5	7.5	8.4

Delivery sizes

Format		L mm	W mm	H mm
Ingots*	1 kg	325	28	15
	4 kg	300	50	40
Ingots with hole	3,7 kg	540	50	20
	6 kg	570	48	35
Bar				400x10x10
Pellet				12 x 25
Wire, solid, on reel				Ø 1.0 – 6.0

*Other dimensions available on request.

Composition of the Alloy

Element	SN97C SnAg3.0Cu0.5 in weight-%	SN97Ce SnAg3.0 in weight-%	Critical values in working solder bath*
Sn	Remainder	Remainder	Remainder
Ag	3.0 ± 0.2	3.0 ± 0.2	
Cu	0.5 ± 0.1	max. 0.4	< 0.4 > 0.85
Ni	max. 0.01	Max. 0.01	> 0.1
Al	max. 0.001	max. 0.001	> 0.002
As	max. 0.03	Max. 0.03	> 0.03
Bi	max. 0.03	Max. 0.03	> 0.10
Cd	max. 0.002	max. 0.002	> 0.002
Fe	max. 0.02	Max. 0.02	> 0.03
Pb	max. 0.05	Max. 0.05	> 0.1 (RoHS)
Sb	max. 0.05	Max. 0.05	> 0.05
Zn	max. 0.001	max. 0.001	> 0.005
Au	max. 0.05	Max. 0.05	> 0.5
In	max. 0.05	Max. 0.05	not indicated



*Max. solder bath impurities are not standardized, but are experience values.

Storage Conditions / Durability

Dry storage at room temperature / minimum 2 years

Safety Advice

Before use please refer to the appropriate Material Safety Data Sheet.

The information in this Data Sheet is based on data considered accurate. The measured values stated are based on own measurements, but do not represent assured properties or delivery specifications. Because of the vast number of different materials and applications – also with respect to possible protective rights of third parties – Balver Zinn Josef Jost GmbH & Co. KG **cannot** accept any liability.



OUR GLOBAL PARTNERS FOR LEAD-FREE SOLDERS

Nihon Superior Co., Ltd
 Phone: +81(0) 6-63 80 11 21
 Fax: +81(0) 6-63 80 12 62
 E-mail: info@nihonsuperior.co.jp
 Web page: www.nihonsuperior.co.jp

DKL Metals Ltd., Avontoun Works
 Phone: +44 (0)1506-847710
 Fax: +44 (0)1506-848199
 E-mail: sales@dklmetals.co.uk
 Web page: www.dklmetals.co.uk

Florida CirTech, Inc.
 Phone: +1 (970) 346-8002
 Fax: +1 (970) 346-8331
 E-mail: b.gilbert@fctassembly.com
 Web page: www.fctassembly.com